



# Half Flange Termination 100 Watts, $50\Omega$



#### **Description**

The J100N50X4 is high performance Aluminum Nitride (AIN) half flange termination intended as a cost competitive alternative to Beryllium Oxide (BeO). The termination is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating circulators, and for use in power combiners. The termination is also RoHS compliant!

#### **General Specifications**

Resistive Element Thick Film
Substrate AIN Ceramic
Cover Alumina Ceramic

Mounting Flange Copper, nickel plated per QC-N-290

**Leads** 99% pure silver (.006" thick)

**Cover** Alumina Ceramic

Tolerance is  $\pm 0.010$ ", unless otherwise specified. Designed to meet of exceed applicable portions of MIL-E-5400. All dimensions in inches.

## Features:

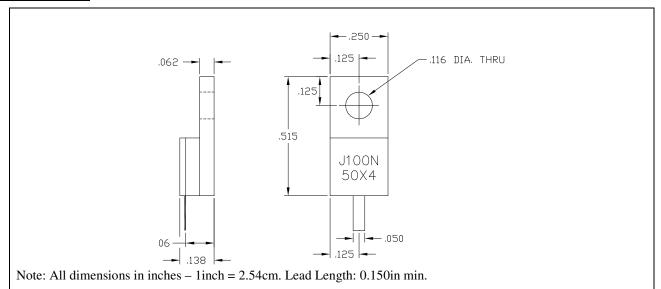
- RoHS Compliant
- 100 Watts
- DC 3.0 GHz
- AIN Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

#### **Electrical Specifications**

Resistance Value:50 Ohms,  $\pm$  2%Power:100 WattsFrequency Range:DC - 3.0GHzV.S.W.R.1.25 : 1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. Storage temperature is -20 °C to 85 °C. Operating temperature is -55 °C to 125 °C (see chart for derating temperatures). **Specifications subject to change with out notice.** 

#### **Outline Drawing**



J100N50X4 (097) Rev D.

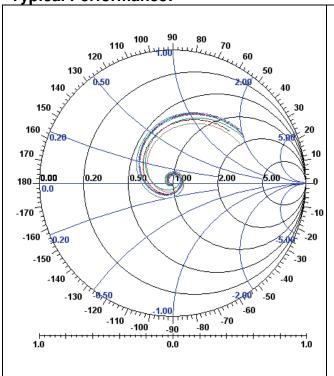


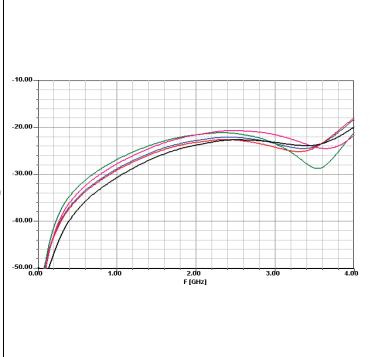
USA/Canada: (315) 432-8909 Toll Free: (800) 544-2414 Europe: +44 2392-232392





**Typical Performance:** 

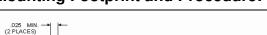




#### **Power De-rating:**

# 100 75 OB EXAME 25 0 25 50 75 100 125 150 CASE TEMPERATURE - °C

## **Mounting Footprint and Procedure:**



BOARD LOWER BOARD EVEN WITH LEAD.

SUGGESTED STRESS RELIEF METHODS

SCALE: NONE

# BOARD LIGHER THAN LEAD. NOT RECOMMENDED APPLICATION

SCALE: NONE

#### SUGGESTED MOUNTING PROCEDURES:

- MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
- DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
- 3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
- 4. POSITION DEVICE ON MOUNTING SURFACE & SECURE
  USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER.
  TORQUE SCREWS TO THE APPROPRIATE VALUE.
  SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK.
  (CARE SHOULD BE TAKENTO AVOID UPWARD PRESSURE OF
  THE LEADS TOWARDS THE LID).
- 5. SOLDER LEADS IN PLACE USING LEAD FREE TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON

\*\* FOR MORE DETAILS CONTACT FACTORY \*\*

J100N50X4 (097) Rev D

USA/Canada: Toll Free: Europe: (315) 432-8909 (800) 544-2414 +44 2392-232392

